

Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating ; RoHS compliant

Parameter	Rating	Units
V_{DS}	650	V
I_D @ 25°C	122	A
$R_{DS(on)}$	15	m Ω



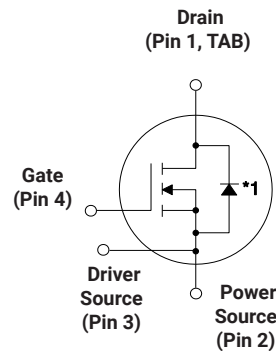
Applications

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating



TO-247-4
Package

Inner circuit



- (1) Drain
- (2) Power Source
- (3) Driver Source
- (4) Gate

*1 Body Diode

Maximum Ratings ($T_c=25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameter	Value	Unit	Note
V_{DSmax}	Drain - Source Voltage	650	V	
V_{GSmax}	Gate - Source voltage	-8/+19	V	
I_D	Continuous Drain Current, $V_{GS} = 15\text{ V}$, $T_c = 25^\circ\text{C}$	122	A	
	Continuous Drain Current, $V_{GS} = 15\text{ V}$, $T_c = 100^\circ\text{C}$	98		
$I_{D(pulse)}$	Pulsed Drain Current, Pulse width t_p limited by T_{jmax}	430	A	
P_D	Power Dissipation, $T_c=25^\circ\text{C}$, $T_j = 175^\circ\text{C}$	420	W	
T_J, T_{stg}	Operating Junction and Storage Temperature	-40 to +175	$^\circ\text{C}$	
T_L	Solder Temperature, 1.6mm (0.063") from case for 10s	260	$^\circ\text{C}$	
M_d	Mounting Torque, (M3 or 6-32 screw)	1	Nm	
		8.8	lbf-in	

Note (1): Recommended turn off / turn on gate voltage $V_{GS} = -4V \dots 0V / +15V$

Note (2): Package limited to 120 A

Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	650			V	$V_{GS} = 0\text{ V}, I_D = 100\text{ }\mu\text{A}$	
$V_{GS(th)}$	Gate Threshold Voltage	1.8	2.3	3.6	V	$V_{DS} = V_{GS}, I_D = 15.5\text{ mA}$	
			1.9		V	$V_{DS} = V_{GS}, I_D = 15.5\text{ mA}, T_J = 175^\circ\text{C}$	
I_{DSS}	Zero Gate Voltage Drain Current		1	50	μA	$V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}$	
I_{GSS}	Gate-Source Leakage Current		10	255	nA	$V_{GS} = 15\text{ V}, V_{DS} = 0\text{ V}$	
$R_{DS(on)}$	Drain-Source On-State Resistance	10.5	15	21	m Ω	$V_{GS} = 15\text{ V}, I_D = 55.8\text{ A}$	
			20			$V_{GS} = 15\text{ V}, I_D = 55.8\text{ A}, T_J = 175^\circ\text{C}$	
g_{fs}	Transconductance		42		S	$V_{DS} = 20\text{ V}, I_{DS} = 55.8\text{ A}$	
			40			$V_{DS} = 20\text{ V}, I_{DS} = 55.8\text{ A}, T_J = 175^\circ\text{C}$	
C_{iss}	Input Capacitance		4960		pF	$V_{GS} = 0\text{ V}, V_{DS} = 400\text{ V}$ $f = 100\text{ KHz}$ $V_{AC} = 25\text{ mV}$	
C_{oss}	Output Capacitance		290				
C_{rss}	Reverse Transfer Capacitance		31				
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		353				
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		516				
E_{oss}	C_{oss} Stored Energy		29		μJ		
E_{ON}	Turn-On Switching Energy (Body Diode)		401		μJ	$V_{DS} = 400\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}, I_D = 55.8\text{ A},$ $R_{G(ext)} = 5\text{ }\Omega, L = 57.6\text{ }\mu\text{H}, T_J = 175^\circ\text{C}$ FWD = Internal Body Diode of MOSFET	
E_{OFF}	Turn Off Switching Energy (Body Diode)		254				
E_{ON}	Turn-On Switching Energy (External Diode)		234		μJ	$V_{DS} = 400\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}, I_D = 55.8\text{ A},$ $R_{G(ext)} = 5\text{ }\Omega, L = 57.6\text{ }\mu\text{H}, T_J = 175^\circ\text{C}$ FWD = External SiC DIODE	
E_{OFF}	Turn Off Switching Energy (External Diode)		310				
$t_{d(on)}$	Turn-On Delay Time		25		ns	$V_{DD} = 400\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}$ $I_D = 55.8\text{ A}, R_{G(ext)} = 5\text{ }\Omega, L = 57.6\text{ }\mu\text{H}$ Timing relative to V_{DS} Inductive load	
t_r	Rise Time		32				
$t_{d(off)}$	Turn-Off Delay Time		60				
t_f	Fall Time		15				
$R_{G(int)}$	Internal Gate Resistance		1.5		Ω	$f = 1\text{ MHz}, V_{AC} = 25\text{ mV}$	
Q_{gs}	Gate to Source Charge		53		nC	$V_{DS} = 400\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}$ $I_D = 55.8\text{ A}$ Per IEC60747-8-4 pg 21	
Q_{gd}	Gate to Drain Charge		62				
Q_g	Total Gate Charge		190				

Note (3): $C_{o(er)}$, a lumped capacitance that gives same stored energy as C_{oss} while V_{ds} is rising from 0 to 400V $C_{o(tr)}$, a lumped capacitance that gives same charging time as C_{oss} while V_{ds} is rising from 0 to 400V

Reverse Diode Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_{SD}	Diode Forward Voltage	4.7		V	$V_{GS} = -4\text{ V}, I_{SD} = 27.9\text{ A}, T_j = 25^\circ\text{C}$	
		4.2		V	$V_{GS} = -4\text{ V}, I_{SD} = 27.9\text{ A}, T_j = 175^\circ\text{C}$	
I_S	Continuous Diode Forward Current		80	A	$V_{GS} = -4\text{ V}, T_c = 25^\circ\text{C}$	
$I_{S, \text{pulse}}$	Diode pulse Current		223	A	$V_{GS} = -4\text{ V}$, pulse width t_p limited by $T_{j\text{max}}$	
t_{rr}	Reverse Recover time	22		ns	$V_{GS} = -4\text{ V}, I_{SD} = 55.8\text{ A}, V_R = 400\text{ V}$ $\text{dif}/\text{dt} = 4000\text{ A}/\mu\text{s}, T_j = 175^\circ\text{C}$	
Q_{rr}	Reverse Recovery Charge	510		nC		
I_{rrm}	Peak Reverse Recovery Current	39		A		
t_{rr}	Reverse Recover time	26		ns	$V_{GS} = -4\text{ V}, I_{SD} = 55.8\text{ A}, V_R = 400\text{ V}$ $\text{dif}/\text{dt} = 2500\text{ A}/\mu\text{s}, T_j = 175^\circ\text{C}$	
Q_{rr}	Reverse Recovery Charge	435		nC		
I_{rrm}	Peak Reverse Recovery Current	28		A		

Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.35	$^\circ\text{C}/\text{W}$		
$R_{\theta JA}$	Thermal Resistance From Junction to Ambient	40			

Package Dimensions

Unit: mm

